

ABSTRACT OF THE DISCLOSURE

A molded interconnect device (MID) having a multilayer circuit of a reduced thickness, in which a layer-to-layer connection(s) is formed with high reliability, is provided as a multilayer circuit board. The multilayer circuit board comprises a substrate having a first surface and a second surface extending from an end of the first surface at a required angle relative to the first surface, and the multilayer circuit formed on the first surface and composed of a plurality of circuit layers. Each of the circuit layers is provided with a conductive layer having a required circuit pattern and an insulation layer formed on the conductive layer by film formation. The layer-to-layer connection of the multilayer circuit is made through a second conductive layer formed on the second surface of the substrate.

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